

Series: Chip Antenna

#### TECHNICAL DATA SHEET

**Description**: 3-in-1 Combo GNSS L1+L2+L5

Ceramic SMD Antenna

PART NUMBER: W3089



### Features:

3 in1 –combo antenna

Port 1: 1170-1249 MHzPort 2: 1559-1608 MHz

Compact size 3.2 x 10 x 2mm

· Omni radiation pattern

SMT mounting on PCB

Tape & Reel packing

MSL-1

## **Applications:**

- Multiband GNSS Receivers
- All bands in one antenna: L1, L2, L5
- GNSS (GPS, Glonass, Beidou, Galileo)
- High precision navigation and location based services

Issue: 2035

In the effort to improve our products, we reserve the right to make changes judged to be necessary. CONFIDENTIAL AND PROPRIETARY INFORMATION

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## **ELECTRICAL SPECIFICATIONS**

Antenna Type ceramic

Frequency 1170-1249MHz; 1559-1608MHz

Nominal Impedance 50  $\Omega$ 

Radiation Pattern Omni

Return Loss 1170-1249MHz <-5

1559-1608 <-8

Gain 1dBi @ 1.2GHz

-1dBi @ 1.6GHz

Efficiency 50% @ 1.2GHz

45% @ 1.6GHz

Polarization Vertical

Power Withstanding 2W



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### **MECHANICAL SPECIFICATIONS**

Weight 0.3 g

Overall Length 10[0.39] MM[INCHES]

Over all width 3.2[0.13] MM[INCHES]

Over all thickness 2[0.08] MM[INCHES]

MSL (Moisture Sensitivity Level) 1

### **ENVIRONMENTAL SPECIFICATIONS**

Operating Temperature -40/+85 ° C

Storage Temperature -10/+30 ° C

RoHS Compliant Yes





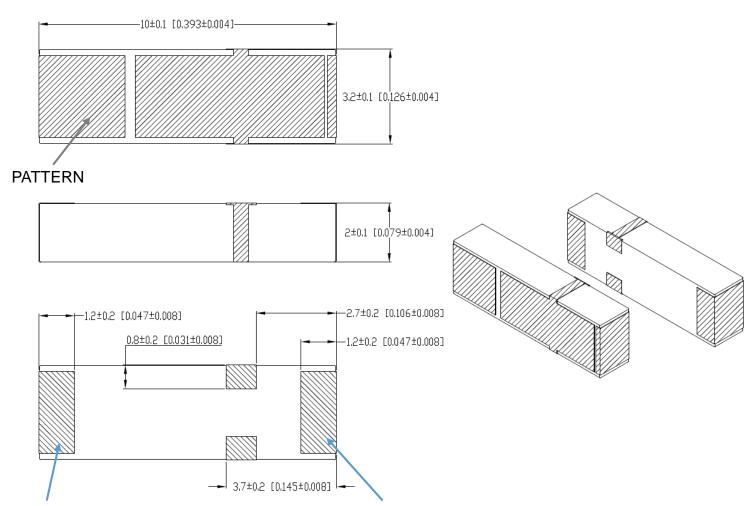
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## **MECHANICAL DRAWING**



Port for 1170-1249 MHz

Port for 1559-1608 MHz



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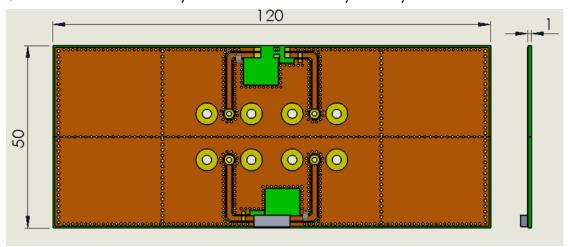
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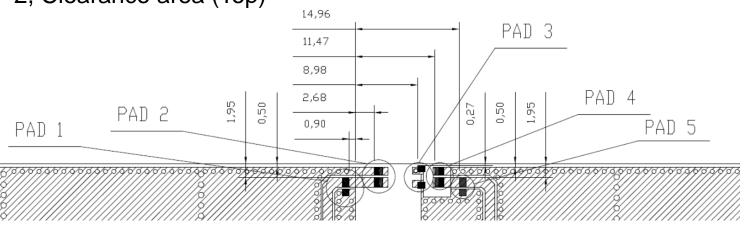
### **OTHER SPECIFICATIONS**

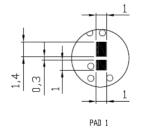
## **PCB LAYOUT**

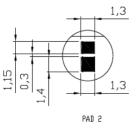
1, PCB material, ISOLA 185HR, size, 120X50X1mm

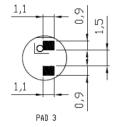


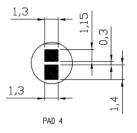
2, Clearance area (Top)

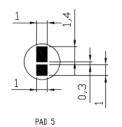














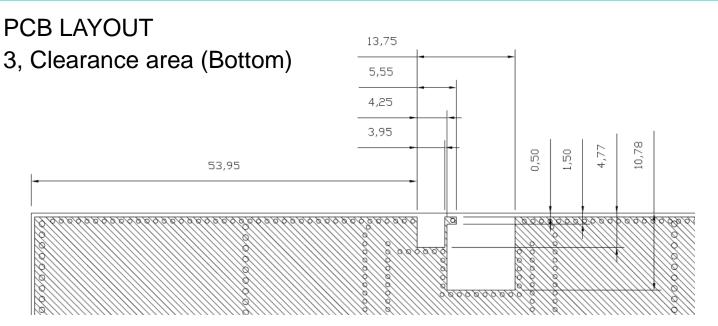
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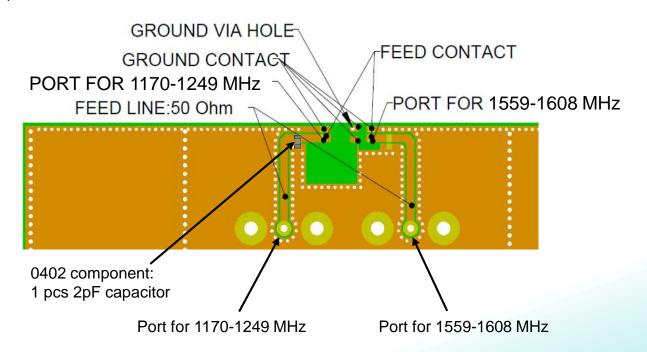
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### **OTHER SPECIFICATIONS**



## 4, PCB Features







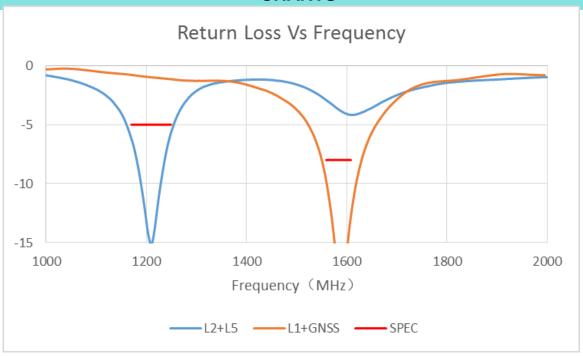
Description: 3-in-1 Combo GNSS L1+L2+L5

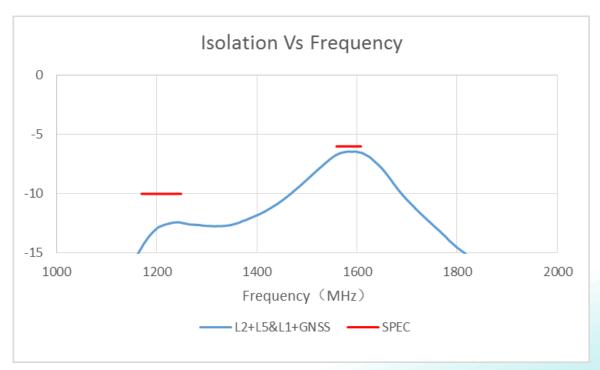
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## **CHARTS**







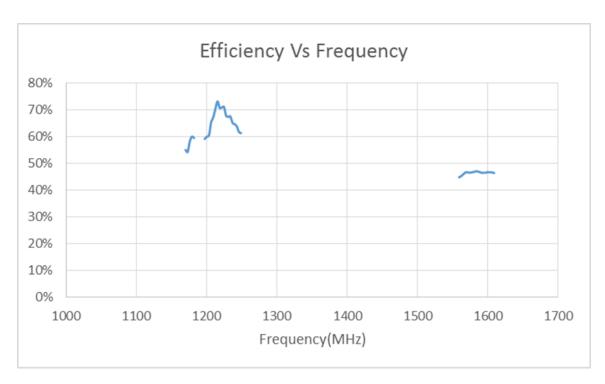
Description: 3-in-1 Combo GNSS L1+L2+L5

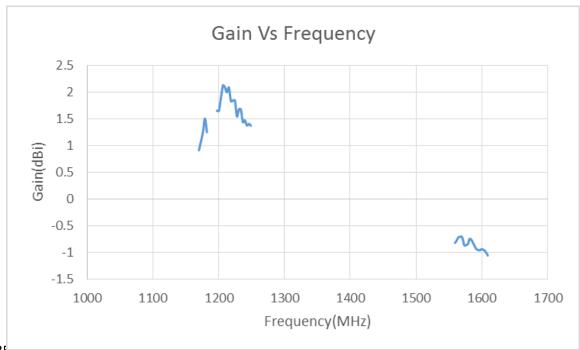
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## **CHARTS**









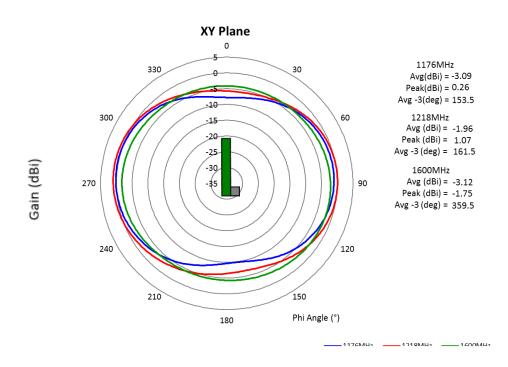
Description: 3-in-1 Combo GNSS L1+L2+L5

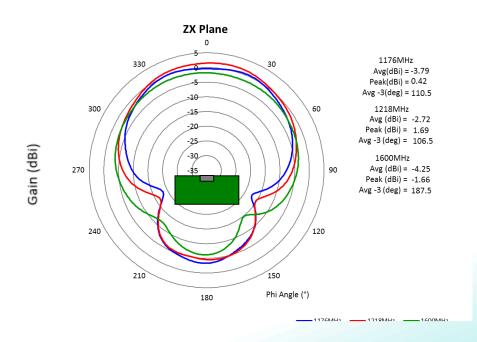
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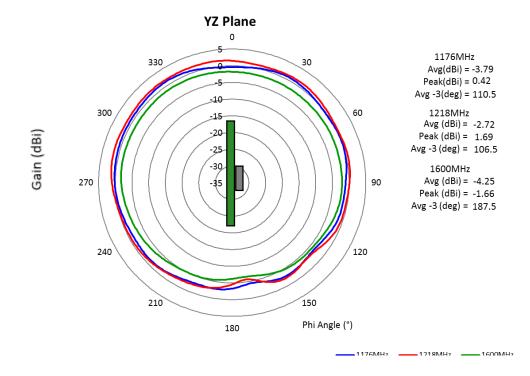
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## **CHARTS**





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## Recommendations for ceramic chip antenna storage

## Storage time

Products should be used within 6 months from the day of manufacturers packaging even when they are stored under below mentioned conditions. Longer storage period may decrease the component solderability.

## Storage environmental conditions

To maintain solderability of Pulse ceramic products care must be taken to control the storage and use conditions:

- Do not store or use products in a corrosive atmosphere, especially where chloride, sulphur or sulfide, alkali or acid salts exist in the air. Corrosive gases may cause oxidation of electrodes and reduce solderability
- Keep temperature and humidity stabile and do not exceed the below mentioned minimum and maximum conditions: Temperature: -10 to +30 Deg C Humidity: below 60% RH
- Do not store the products under direct sun light.

It is recommended to keep the products in manufacturers packing (tape&reel) until the time of assembly and soldering process. Air tight vacuum package is recommended in the conditions where it is know to be some corrosive gases.

## Handling

Do not touch the components with bare hands. Protective gloves must be used to prevent contamination of terminals which may cause reduced solderability. Do not touch or damage the silver plated surface by any sharp objects. Soft materials (plastic, wood etc.) must be used if tweezers or other tools are used to pick the components. Avoid any excess mechanical shock or vibration during storage and handling.



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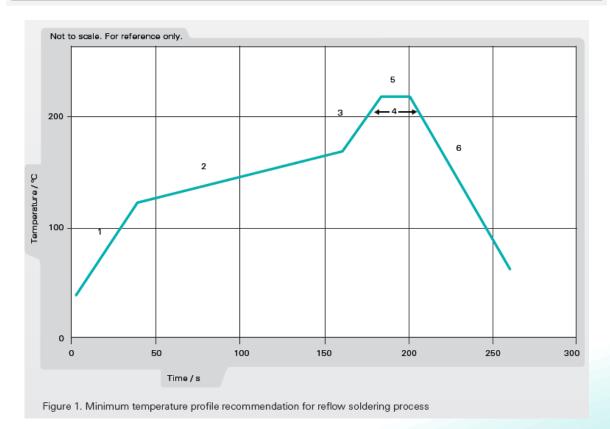
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## **Recommendations for reflow soldering process**

Printing stencil thickness 0,15 - 0,25 mm is recommended for the solder paste. The maximum soldering temperature should not exceed 260°C. The temperature profile recommendations for reflow soldering process is presented in the Figures 1 and 2. The reflow profile presented in figure 1 describes minimum reflow temperatures. The reflow profile presented in figure 2 describes maximum reflow temperatures. located at the center of the coverage area.

	Method of heat transfer	Controlled hot air convection
1	Average temperature gradient in preheating	2.5 °C/s
2	Soak time	2-3 minutes
3	Max temperature gradient in reflow	3 °C/s
4	Time above 217 °C	Max 30 sec
5	Peak temperature in reflow	230 ℃ for 10 seconds
6	Temperature gradient in cooling	Max -5 °C/s



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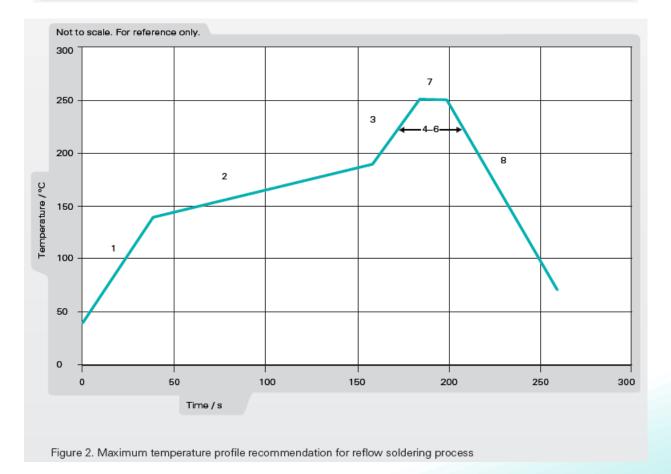
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## Recommendations for reflow soldering process

	Method of heat transfer	Controlled hot air convection
1	Average temperature gradient in preheating	2.5 °C/s
2	Soak time	2-3 minutes
3	Max temperature gradient in reflow	3 °C/s
4	Time above 217 °C	Max 60 sec
5	Time above 230 °C	Max 50 sec
6	Time above 250 °C	Max 10 sec
7	Peak temperature in reflow	260 °C for 5 seconds
8	Temperature gradient in cooling	Max -5 °C/s







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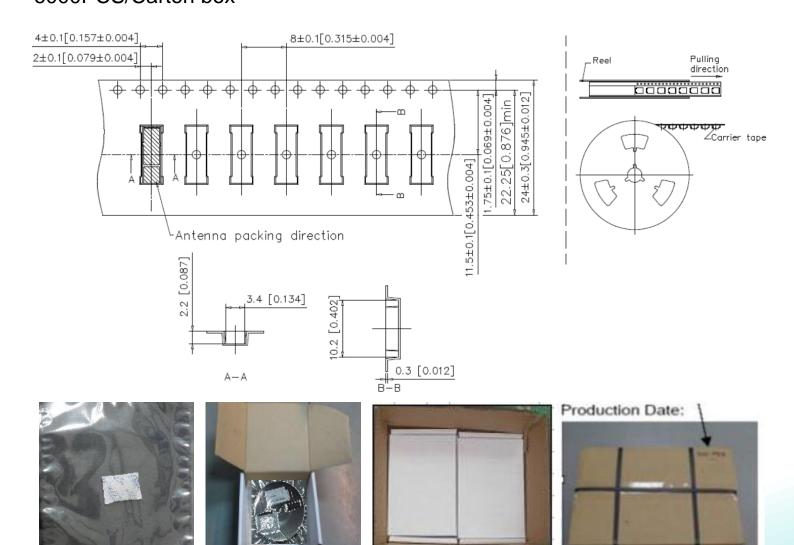
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## **PACKAGING**

Taping package 1000PCS/Reel 3000PCS/Small box 6000PCS/Carton box







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